



Material Content Data Sheet



Sales Product Name				IPD90N03S4L-03		Issued		25. January 2018	
MA#				MA001913364					
Package				PG-TO252-3-11		Weight*		370.70 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	2.247	0.61	0.61	6061	6061	
leadframe	inorganic material	phosphorus	7723-14-0	0.065	0.02		174		
	non noble metal	iron	7439-89-6	0.215	0.06		581		
	non noble metal	copper	7440-50-8	215.017	58.01	58.09	580034	580789	
	non noble metal	aluminium	7429-90-5	4.706	1.27	1.27	12695	12695	
wire	non noble metal	aluminium	7429-90-5	4.706	1.27	1.27	12695	12695	
encapsulation	organic material	carbon black	1333-86-4	1.233	0.33		3325		
	plastics	epoxy resin	-	21.571	5.82		58190		
	inorganic material	silicondioxide	60676-86-0	100.458	27.10	33.25	270997	332512	
leadfinish	non noble metal	tin	7440-31-5	3.740	1.01	1.01	10089	10089	
plating	inorganic material	phosphorus	7723-14-0	0.000	0.00		1		
	non noble metal	nickel	7440-02-0	0.091	0.02	0.02	245	246	
solder	non noble metal	tin	7440-31-5	0.043	0.01		116		
	noble metal	silver	7440-22-4	0.054	0.01		145		
	non noble metal	lead	7439-92-1	2.056	0.55	0.57	5545	5806	
heatspreader	inorganic material	phosphorus	7723-14-0	0.006	0.00		16		
	non noble metal	iron	7439-89-6	0.019	0.01		52		
	non noble metal	copper	7440-50-8	19.177	5.17	5.18	51734	51802	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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